



Click [here](#) for the 3D model.

General Information

Series	SMD Comm COG Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
Termination	Flexible Termination With Lead (SnPb)
Marking	false
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.15mm
S	0.4mm MIN
B	0.45mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

Specifications

Capacitance	2.2 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	+/-0.5 pF
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.